

Specifications

Mechanics

X, Y table Working area 100 x 100 mm
Resolution 0.25 µm, repeatability < 2 µm

Z-axis 60 mm

Speed All axes programmable from 0.2...16 mm/s
30 wires / min.

Bond head

Gold Ball-Wedge
Negative flame-off unit
F & K 60 KHz US standard, 100 KHz optional
Wire diameter 17.5 ... 50 µm

Control

Heating Integrated in machine 0-300°C

Computer Single-Board PC, 600 MHz Pentium processor, 256 MB RAM, ethernet, USB 4x, CD-ROM

Monitor 15" TFT flat screen

Operation system Windows 2000

Printer All Windows-compatible printers can be installed
All bonding parameters can be printed

Heated work holder Ø 60mm, optional Ø 80mm and 4x4"

Rev. 04
03_2005



5610

Semi-automatic Gold Ball Bonder

The semi-automatic Gold Ball-Bonder 5610 fills the gap between the manual and semi-automatic Ball Bonder series 5410 and the fully automatic Ball Bonders from F&K Delvotec. The 5610 is fully PC controlled and allows any number of bonds and bumps to be programmed. Pre-programmed adjust points are targeted through the camera's cross hair targeting system and the programmed bonds or bumps are executed automatically. Two operating modes are available: Single bond for repair of various bond samples and making single bonds (manual-automatic) and multi wire for teaching and bonding chips or various bond samples (semi and fully automatic).

The 5610 can also be used as Thin Wire Wedge Wedge or Heavy Wire as well as pull-/shear tester by simply replacing the bond head and loading the appropriate software. Set-up time: approx. 5 minutes. Ask for information

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Other features

Programming

Automatic bonding of hybrids or COB with programmable X/Y table

Work holders

Standard



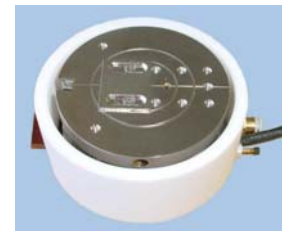
for components up to 60 mm Ø
mechanical clamping
heated

optional



for components up to 4" x 4"
vacuum and mechanical clamping
heated

optional



for components up to 80 mm Ø
vacuum and mechanical clamping
heated

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Head Parking System

For storing of temporary not required bondhead or pull-, shear-, peel- and tweezer heads.
Can be mounted on the left or right side of the machine

General

Camera

With cross hair targeting for positioning of bonds

Microscope

Stereoscope Leica S6, other microscopes optional

Lighting

20 W halogen spot light and LED direct light

Dimensions

Height 70 cm, width 70 cm, depth 65 cm; approx. 70 kg

Supplies

100...240 VAC, single-phase, 50/60 Hz, max. 500 VA;

Connections

Air 6 bar; vacuum 0,7 bar

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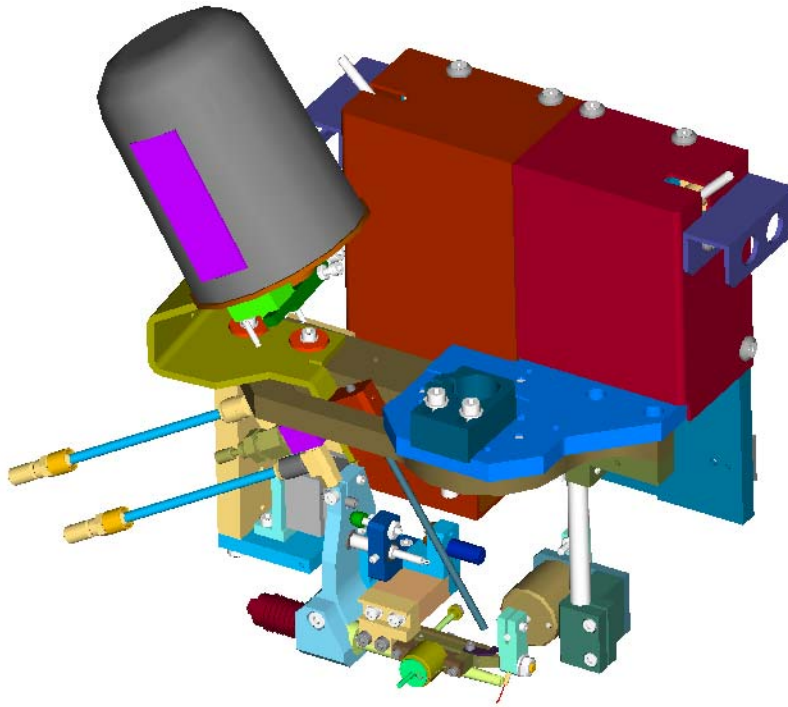
Retro-fit-head 56xx

Bondhead 5610

Wire size Au 17,5 - 50 µm

Bonding Capillaries up to 16 mm usable

Ball-Wedge / Stud-Bumping



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